

ABSTRACT

Resin Sealing Type Semiconductor Device and Method of Making the Same

A resin sealing type semiconductor device has first and second heat radiating portions located on opposite sides of a semiconductor element. The first heat radiating portion has an element placing surface. A plurality of leads are disposed at a given distance from the semiconductor element, and connected to the electrode pads through wires. The second heat radiating portion is located in non-contact with the semiconductor element, leads and wires. A first insulating portion is located between the first heat radiating portion and the leads. A second insulating portion is located between the second heat radiating portion and the leads. Preferably, the first insulating portion is formed continuously on one side of the first heat radiating portion, and the second insulating portion on one side of the second heat radiating portion. A space enclosed by these insulating and heat radiating portions houses the semiconductor element, the wires and the tips of the leads.

Fig. 1.